

# NBXSGA008

## 2.5/3.3 V, 161.1328 MHz LVPECL Clock Oscillator

The NBXSGA008, single frequency, crystal oscillator (XO) is designed to meet today's requirements for 2.5/3.3 V LVPECL clock generation applications. The device uses a high Q fundamental crystal and Phase Lock Loop (PLL) multiplier to provide 161.1328 MHz, ultra low jitter and phase noise LVPECL differential output.

This device is a member of ON Semiconductor's PureEdge™ clock family that provides accurate and precision clock solutions.

Available in 5 mm x 7 mm SMD (CLCC) package on 16 mm tape and reel in quantities of 100 and 1,000.

### Features

- LVPECL Differential Output
- Uses High Q Fundamental Mode Crystal and PLL Multiplier
- Ultra Low Jitter and Phase Noise – 0.5 ps (12 kHz – 20 MHz)
- Output Frequency – 161.1328 MHz
- Hermetically Sealed Ceramic SMD Package
- RoHS Compliant
- Operating Range: 2.5 V  $\pm 5\%$  or 3.3 V  $\pm 10\%$
- Total Frequency Stability –  $\pm 50$  PPM
- This is a Pb-Free Device

### Applications

- Networking / Telecom
- Storage
- 10 GE
- WLAN

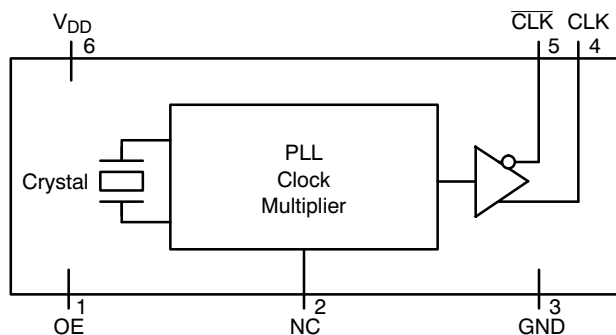
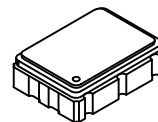


Figure 1. Simplified Logic Diagram



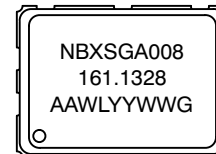
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6 PIN CLCC  
LN SUFFIX  
CASE 848AB

### MARKING DIAGRAM



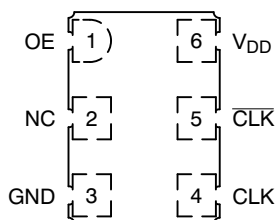
NBXSGA008 = NBXSGA008 ( $\pm 50$  PPM)  
161.1328 = Output Frequency (MHz)  
AA = Assembly Location  
WL = Wafer Lot  
YY = Year  
WW = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping†
NBXSGA008LN1TAG	CLCC-6 (Pb-Free)	1000/Tape & Reel
NBXSGA008LNHTAG	CLCC-6 (Pb-Free)	100/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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**Figure 2. Pin Connections** (Top View)

**Table 1. PIN DESCRIPTION**

Pin No.	Symbol	I/O	Description
1	OE	LVTTTL/LVCMOS Control Input	Output Enable Pin. When left floating pin defaults to logic HIGH and output is active. See OE pin description Table 2.
2	NC	N/A	No Connect.
3	GND	Power Supply	Ground 0 V
4	CLK	LVPECL Output	Non-Inverted Clock Output. Typically loaded with 50 $\Omega$ receiver termination resistor to $V_{TT} = V_{DD} - 2 V$ .
5	$\overline{\text{CLK}}$	LVPECL Output	Inverted Clock Output. Typically loaded with 50 $\Omega$ receiver termination resistor to $V_{TT} = V_{DD} - 2 V$ .
6	V <sub>DD</sub>	Power Supply	Positive power supply voltage. Voltage should not exceed 2.5 V $\pm$ 5% or 3.3 V $\pm$ 10%.

**Table 2. OUTPUT ENABLE TRI-STATE FUNCTION**

OE Pin	Output Pins
Open	Active
HIGH Level	Active
LOW Level	High Z

**Table 3. ATTRIBUTES**

Characteristic	Value
Internal Default State Resistor	170 k $\Omega$
ESD Protection	Human Body Model Machine Model
	2 kV 200 V
Meets or Exceeds JEDEC Standard EIA/JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

**Table 4. MAXIMUM RATINGS**

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V <sub>DD</sub>	Positive Power Supply	GND = 0 V		4.6	V
I <sub>out</sub>	LVPECL Output Current	Continuous Surge		25 50	mA
T <sub>A</sub>	Operating Temperature Range			-40 to +85	$^{\circ}\text{C}$
T <sub>stg</sub>	Storage Temperature Range			-55 to +120	$^{\circ}\text{C}$
T <sub>sol</sub>	Wave Solder	See Figure 5		260	$^{\circ}\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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**Table 5. DC CHARACTERISTICS** ( $V_{DD} = 2.5\text{ V} \pm 5\%$ ;  $3.3\text{ V} \pm 10\%$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ) (Note 2)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
$I_{DD}$	Power Supply Current			91	105	mA
$V_{IH}$	OE Input HIGH Voltage		2000		$V_{DD}$	mV
$V_{IL}$	OE Input LOW Voltage		$GND - 300$		800	mV
$I_{IH}$	Input HIGH Current	OE	-100		+100	$\mu\text{A}$
$I_{IL}$	Input LOW Current	OE	-100		+100	$\mu\text{A}$
$V_{OH}$	Output HIGH Voltage		$V_{DD}-1195$		$V_{DD}-945$	mV
$V_{OL}$	Output LOW Voltage		$V_{DD}-1945$		$V_{DD}-1600$	mV
$V_{OUTPP}$	Output Voltage Amplitude			700		mV

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Measurement taken with outputs terminated with  $50\ \Omega$  to  $V_{DD} - 2.0\text{ V}$ . See Figure 4.

**Table 6. AC CHARACTERISTICS** ( $V_{DD} = 2.5\text{ V} \pm 5\%$ ;  $3.3\text{ V} \pm 10\%$ ,  $GND = 0\text{ V}$ ,  $T_A = -40^\circ\text{C}$  to  $+85^\circ\text{C}$ ) (Note 3)

Symbol	Characteristic	Conditions	Min.	Typ.	Max.	Units
$f_{CLKOUT}$	Output Clock Frequency			161.1328		MHz
$\Delta f$	Frequency Stability – NBXSGA008	(Note 4)			$\pm 50$	ppm
$\Phi_{NOISE}$	Phase-Noise Performance $f_{CLKout} = 161.1328\text{ MHz}$ (See Figure 3)	100 Hz of Carrier		-99		dBc/Hz
		1 kHz of Carrier		-119		dBc/Hz
		10 kHz of Carrier		-126		dBc/Hz
		100 kHz of Carrier		-127		dBc/Hz
		1 MHz of Carrier		-135		dBc/Hz
		10 MHz of Carrier		-160		dBc/Hz
$t_{jit}(\Phi)$	RMS Phase Jitter	12 kHz to 20 MHz		0.5	0.7	ps
$t_{jitter}$	Cycle to Cycle, RMS	1000 Cycles		1.6	8	ps
	Cycle to Cycle, Peak-to-Peak	1000 Cycles		10	30	ps
	Period, RMS	10,000 Cycles		1	4	ps
	Period, Peak-to-Peak	10,000 Cycles		7	20	ps
$t_{OE/OD}$	Output Enable/Disable Time				200	ns
$t_{DUTY\_CYCLE}$	Output Clock Duty Cycle (Measured at Cross Point)		48	50	52	%
$t_R$	Output Rise Time (20% and 80%)			250	400	ps
$t_F$	Output Fall Time (80% and 20%)			250	400	ps
$t_{start}$	Start-up Time			1	5	ms
	Aging	1 <sup>st</sup> Year			3	ppm
		Every Year After 1 <sup>st</sup>			1	ppm

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

3. Measurement taken with outputs terminated with  $50\ \Omega$  to  $V_{DD} - 2.0\text{ V}$ . See Figure 4.

4. Parameter guarantees 10 years of aging. Includes initial stability at  $25^\circ\text{C}$ , shock, vibration, and first year aging.

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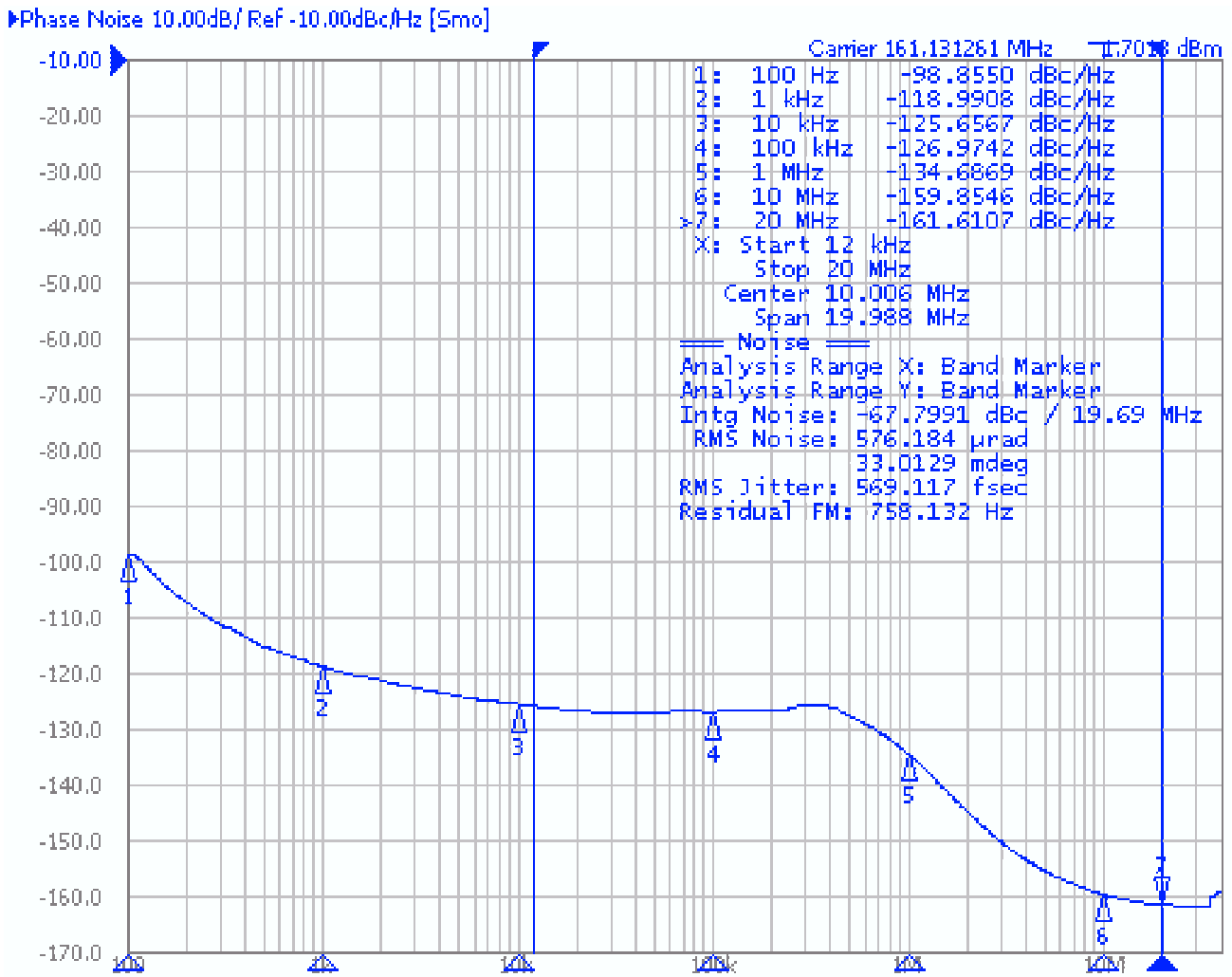
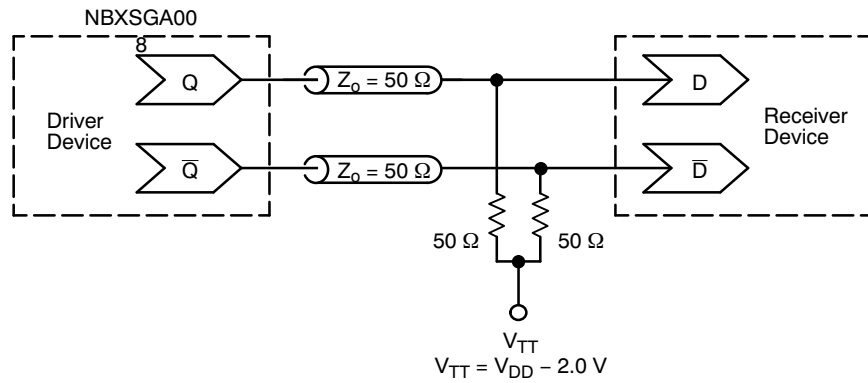


Figure 3. Typical Phase Noise Plot

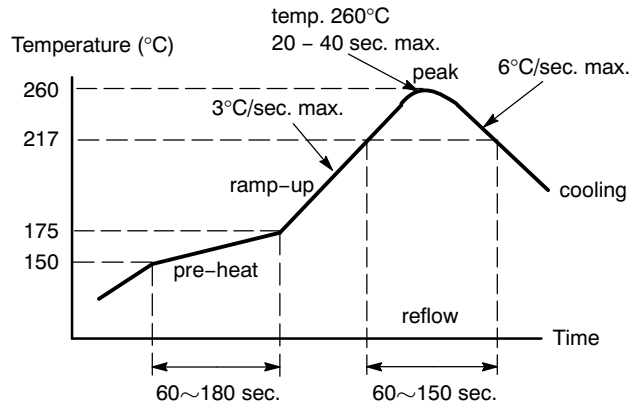
Table 7. RELIABILITY COMPLIANCE

Parameter	Standard	Method
Shock	Mechanical	MIL-STD-833, Method 2002, Condition B
Solderability	Mechanical	MIL-STD-833, Method 2003
Vibration	Mechanical	MIL-STD-833, Method 2007, Condition A
Solvent Resistance	Mechanical	MIL-STD-202, Method 215
Thermal Shock	Environment	MIL-STD-833, Method 1011, Condition A
Moisture Level Sensitivity	Environment	MSL1 260°C per IPC/JEDEC J-STD-020D

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**Figure 4. Typical Termination for Output Driver and Device Evaluation**  
 (See Application Note AND8020/D – Termination of ECL Logic Devices.)

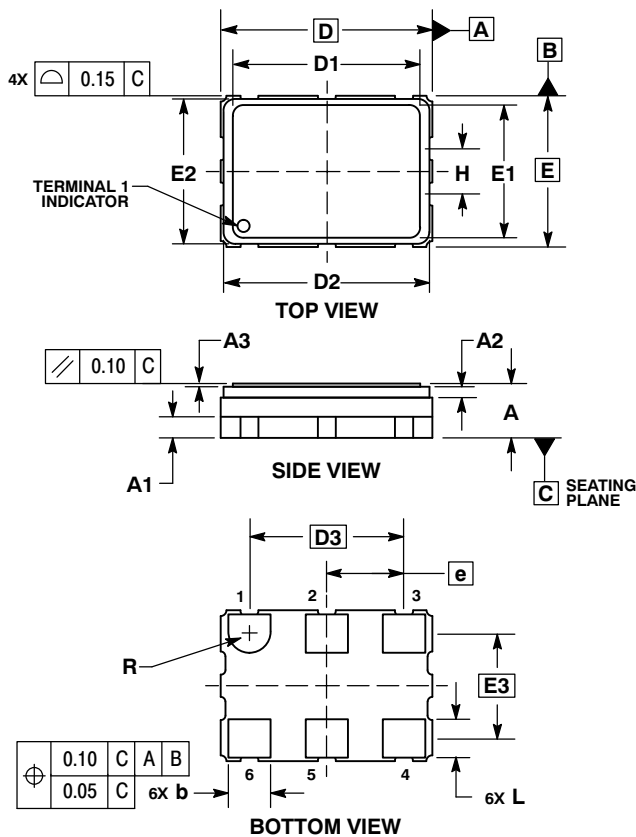


**Figure 5. Recommended Reflow Soldering Profile**

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## PACKAGE DIMENSIONS

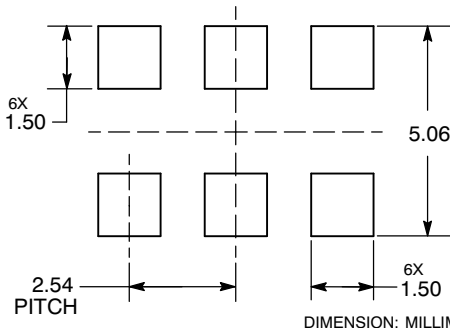
6 PIN CLCC, 7x5, 2.54P  
CASE 848AB-01  
ISSUE C



- NOTES:  
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.  
2. CONTROLLING DIMENSION: MILLIMETERS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	1.70	1.80	1.90
A1	0.70 REF		
A2	0.36 REF		
A3	0.08	0.10	0.12
b	1.30	1.40	1.50
D	7.00 BSC		
D1	6.17	6.20	6.23
D2	6.66	6.81	6.96
D3	5.08 BSC		
E	5.00 BSC		
E1	4.37	4.40	4.43
E2	4.65	4.80	4.95
E3	3.49 BSC		
e	2.54 BSC		
H	1.80 REF		
L	1.17	1.27	1.37
R	0.70 REF		

### SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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